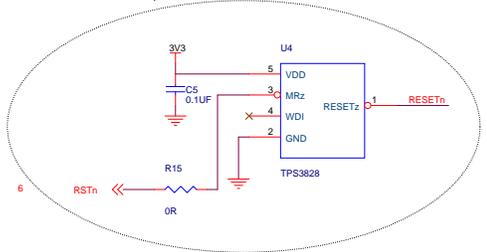


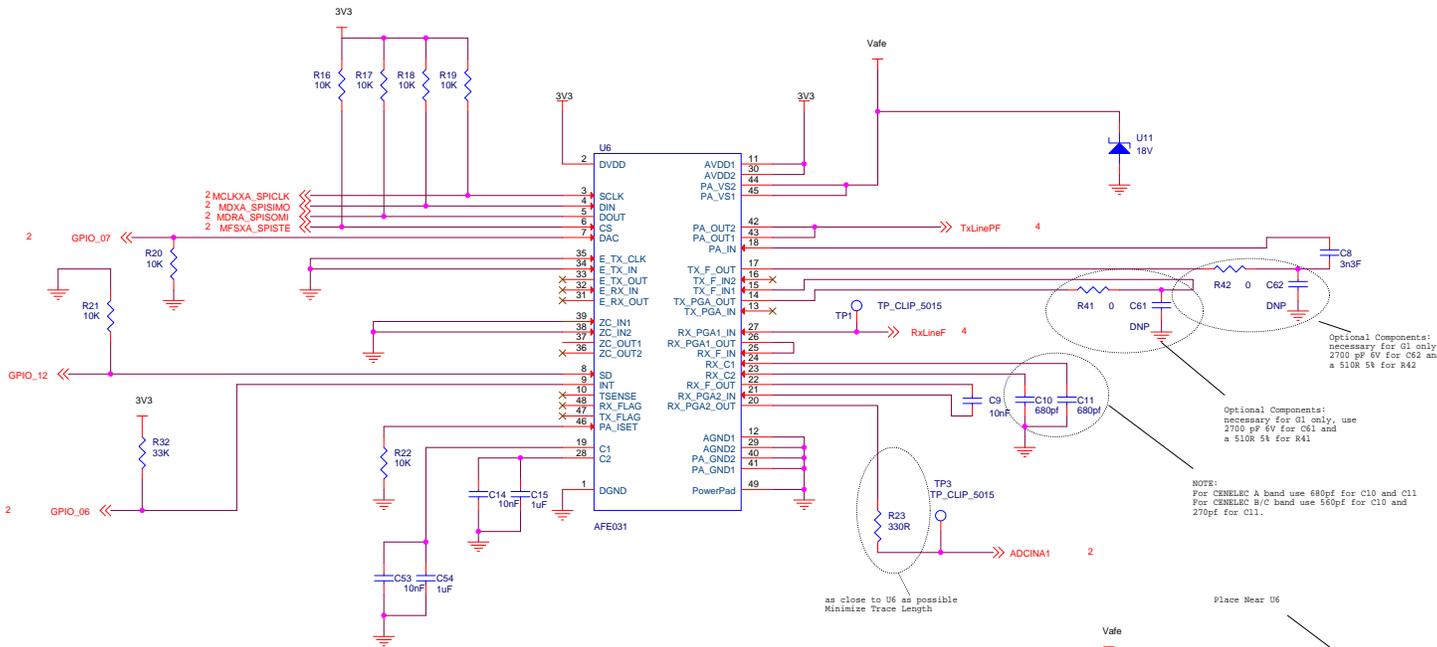
OPTIONAL if BOR is handled by the system or Host processor



Bootmode selection can be hard wired if required modes are known.

TIDM-SOMPLC-03-CENELEC			
Title: TI PLC F29069 SOM MODULE			
Page Contents: 02 - MCU			
Size: B	<Doc>	Revision: 0.18	
Date: Friday, July 11, 2014	Sheet 2 of 6		



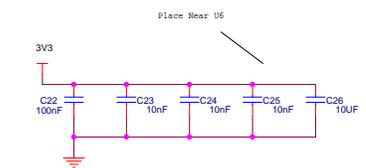
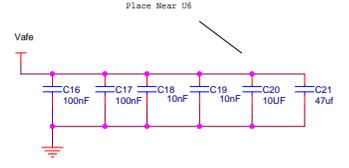


U6 MUST BE on TOP (OUTER, FREE-AIR) side of board!!!!

Optional Components:
 necessary for G1 only, use
 2700 pF 6V for C62 and
 a 510R 5% for R42

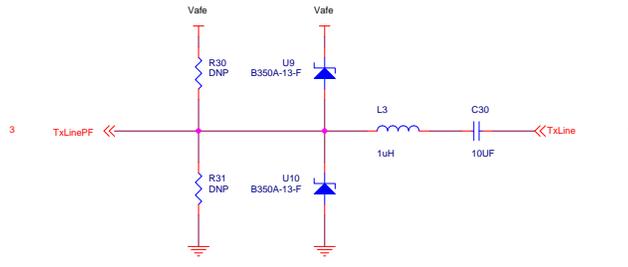
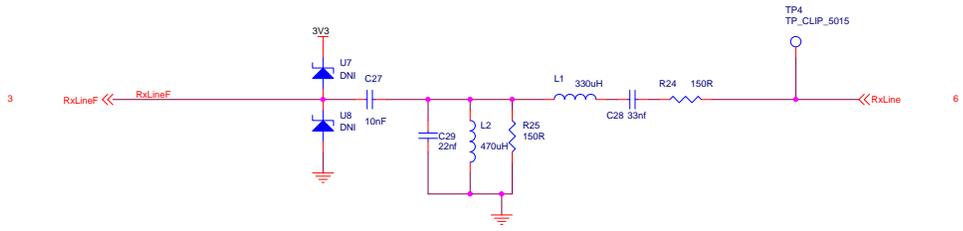
Optional Components:
 necessary for G3 only, use
 2700 pF 6V for C61 and
 a 510R 5% for R41

NOTE:
 For CENELEC A band use 680pf for C10 and C11
 For CENELEC B/C band use 560pf for C10 and
 270pf for C11.



TIDM-SOMPLC-G3-CENELEC			
Title: TI PLC F29069 SOM MODULE			
Page Contents: 03 - AFE031			
Size:B	<Doc>	Revision: 0.1B	
Date:	Friday, July 11, 2014	Sheet 3 of	6

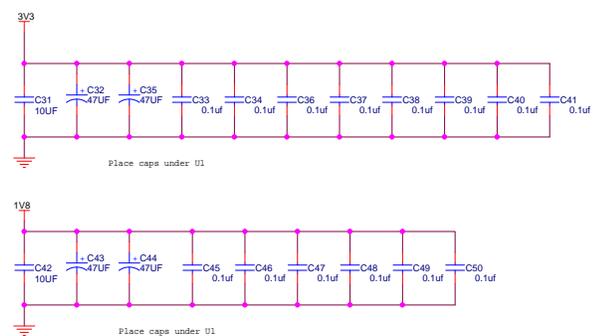
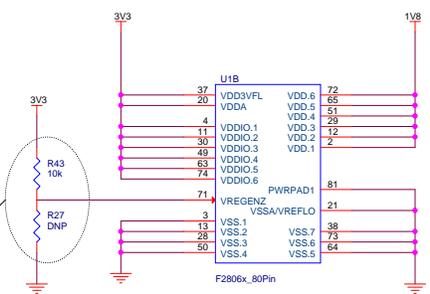
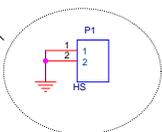




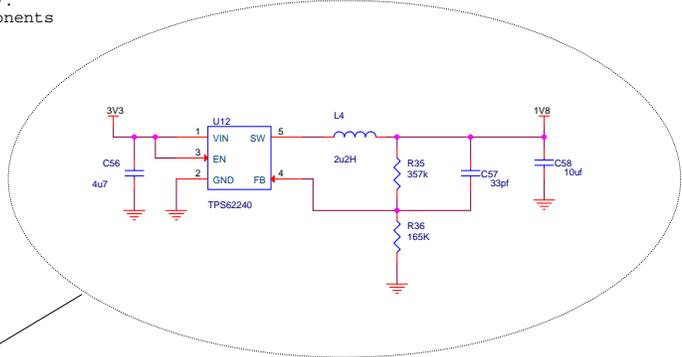
NOTE: Several components on this page have been removed or changed in the BOM.

TIDM-SOMPLC-03-CENELEC			TI
Title: TI PLC F29069 SOM MODULE			
Page Contents: 04 - AFE1 (Passive RX Filter)			Revision: 0.18
Size: B	<Doc>		
Date: Friday, July 11, 2014	Sheet 4 of 6		

OPTIONAL: Heatsink is not needed.

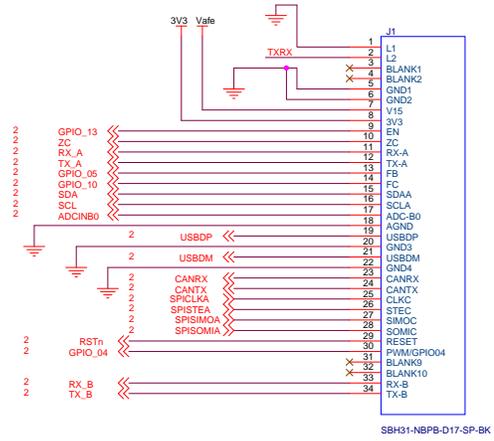
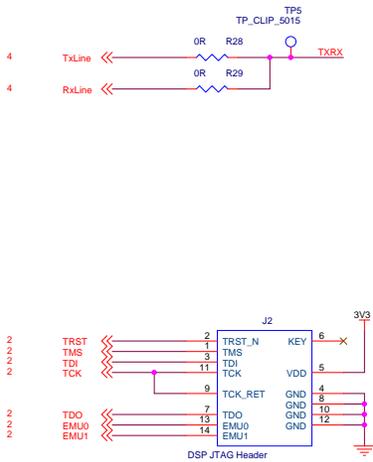


OPTIONAL: to source VDD with the on chip LDO, do not populate R43 and place a 10k resistor on R27. Additionally, the optional components below are not needed.



OPTIONAL: For reduced power consumption use a DC/DC converter instead of the On-Chip Linear Supply. Note: Follow Layout Procedures described in TP562240 Datasheet

TIIM-SOMPLC-03-CBNELEC		TI
Title: TI PLC F28069 SOM MODULE		
Page Contents: 05 - Power		
Size: B	<Doc>	Revision: 0.1B
Date: Friday, July 11, 2014	Sheet 5 of 6	6



TI	
TIPLC-F29069-SOM-MODULE	
Page Contents: 06 - Connector	
Size: B	Revision: 0.18
Date: Friday, July 11, 2014	Sheet 6 of 6

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